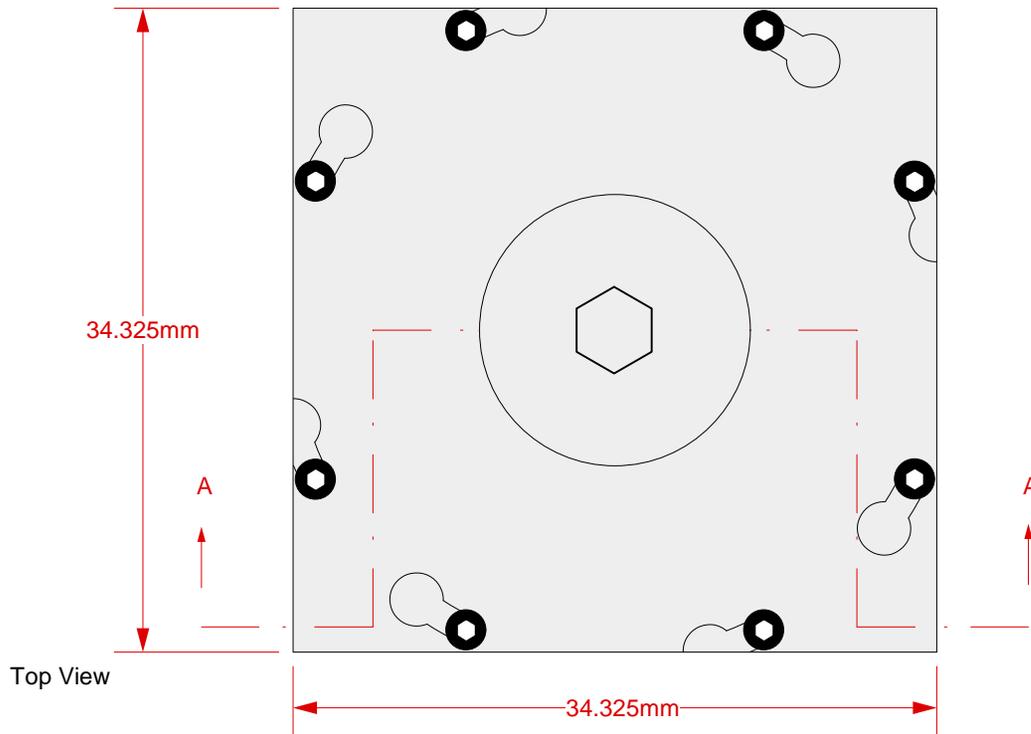


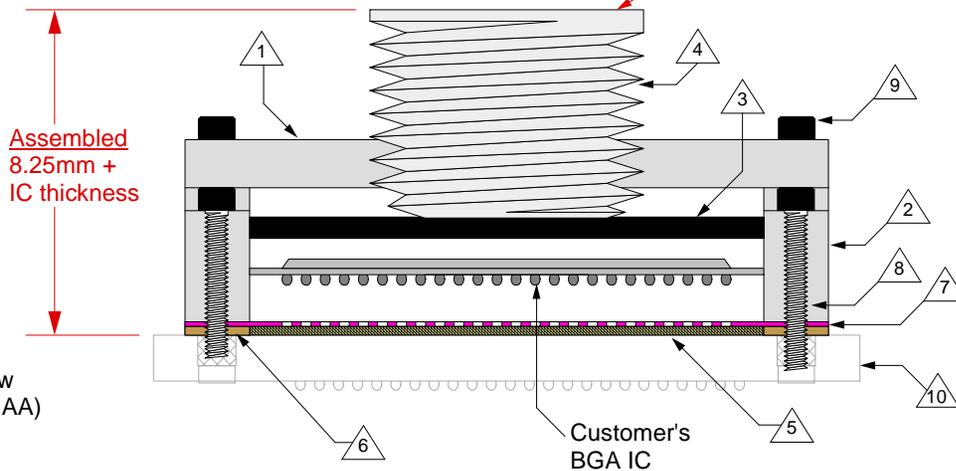
GHz BGA SMT Socket

Features

- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



Top View



Side View
(Section AA)

- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 6.5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Cirlex or equivalent. Thickness = 0.75mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 SMT Adapter: Ironwood Part number- 3.125mm thickness. (not included)

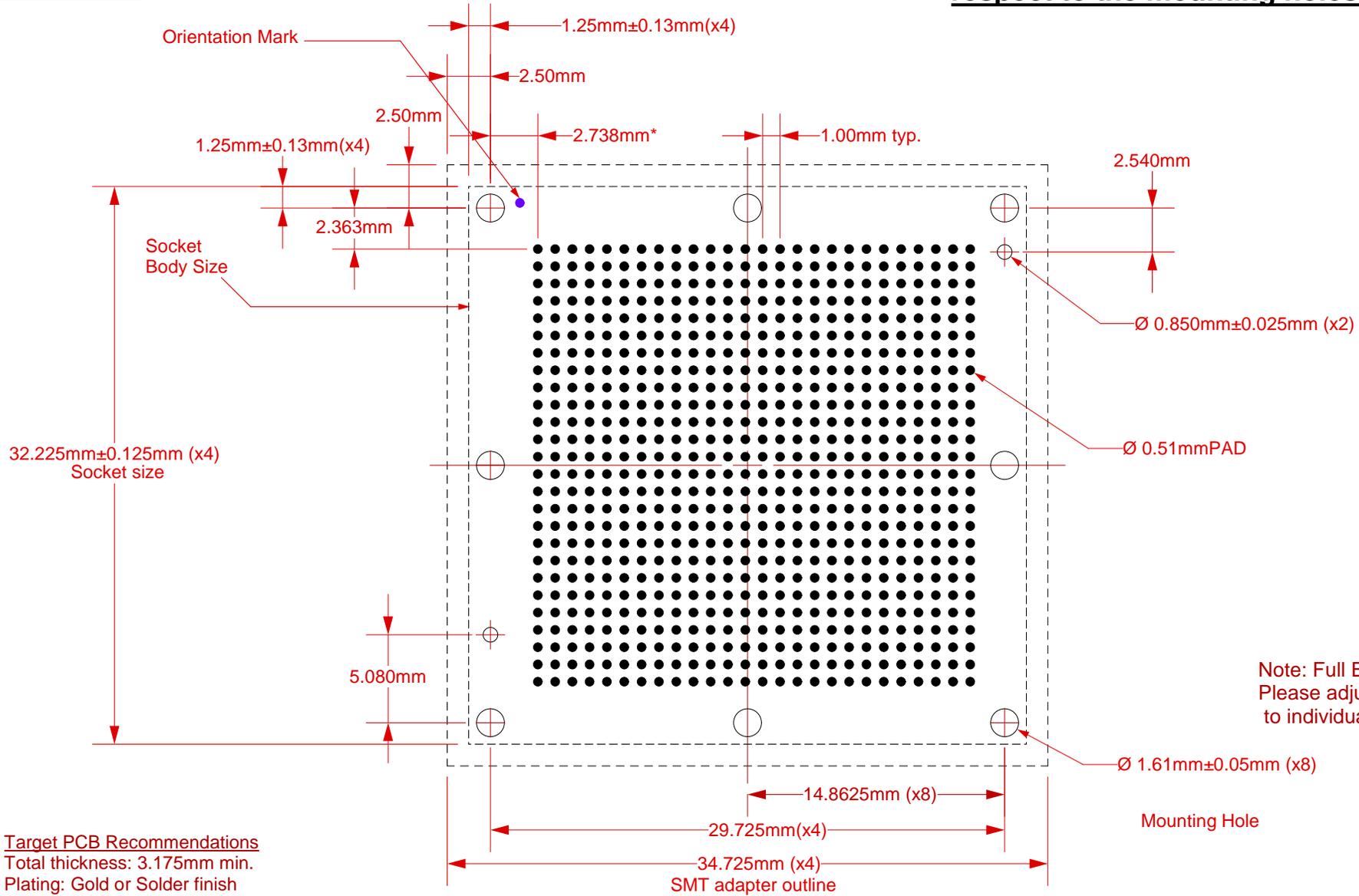
Socket is used with Ironwood's SMT adapter - (sold separately)

 <p>© 2012 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>SG-BGA-6364 Drawing</p>	<p>Status: Released</p>	<p>Scale: NA</p>	<p>Rev: A</p>
	<p>Drawing: V. Panavala</p>	<p>Date: 8/29/2012</p>		
	<p>File: SG-BGA-6364 Dwg.mcd</p>	<p>Modified:</p>		

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View: IF USED WITHOUT
SMT ADAPTER

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



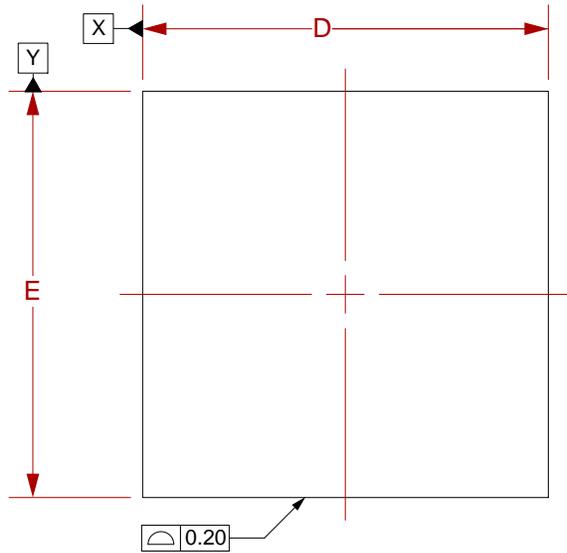
Note: Full BGA pattern shown. Please adjust pattern according to individual requirements.

Target PCB Recommendations
 Total thickness: 3.175mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

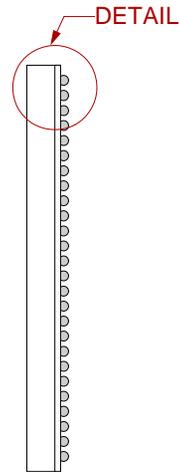
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

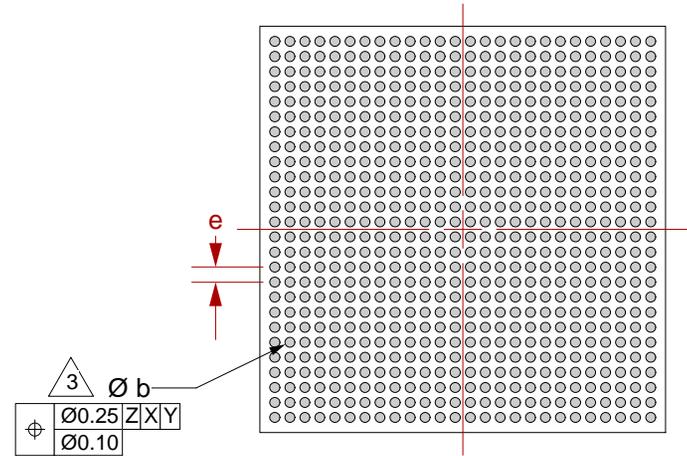
SG-BGA-6364 Drawing		Status: Released	Scale: 2:1	Rev: A
 © 2012 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: V. Panavala		Date: 8/29/2012	
	File: SG-BGA-6364 Dwg.mcd		Modified:	



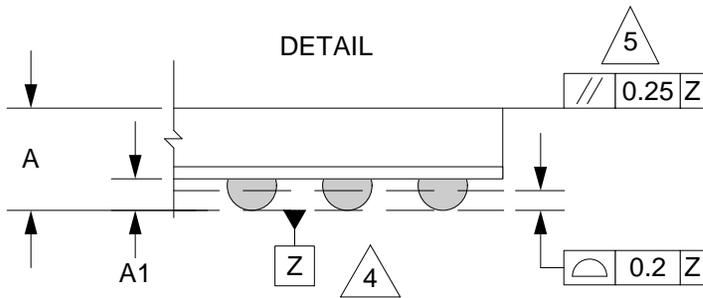
TOP VIEW



SIDE VIEW



BOTTOM VIEW



1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.5
A1	0.4	0.6
b		0.7
D	27.0 BSC	
E	27.0 BSC	
e	1.00 BSC	

Array 26 x 26

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	Drawing: V. Panavala		Date: 8/29/2012	
	File: SG-BGA-6364 Dwg.mcd		Modified:	